# **Quad OR/NOR Gate**

### **Description**

The MC10H101 is a quad 2-input OR/NOR gate with one input from each gate common to pin 12. This MECL 10HTM part is a functional/pinout duplication of the standard MECL 10K<sup>TM</sup> family part, with 100% improvement in propagation delay, and no increases in power-supply current.

#### **Features**

- Propagation Delay, 1.0 ns Typical
- Power Dissipation 25 mW/Gate (same as MECL 10K)
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K Compatible
- Pb-Free Packages are Available\*



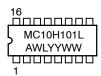
#### ON Semiconductor®

http://onsemi.com

#### **MARKING DIAGRAMS\***



CDIP-16 **L SUFFIX CASE 620** 



MC10H101P **AWLYYWWG** 

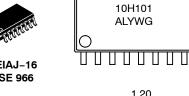
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PDIP-16 **P SUFFIX CASE 648** 

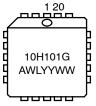


SOEIAJ-16 **CASE 966** 





PLLC-20 **FN SUFFIX CASE 775** 



= Assembly Location

WL, L = Wafer Lot YY, Y = Year WW. W = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

\*For additional marking information, refer to Application Note AND8002/D.

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

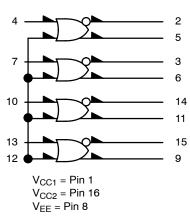
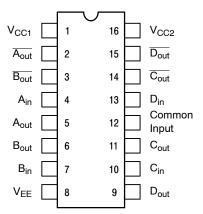


Figure 1. Logic Diagram



Pin assignment is for Dual-in-Line Package.

Figure 2. Pin Assignment

**Table 1. MAXIMUM RATINGS** 

Symbol	Characteristic		Rating	Unit
V <sub>EE</sub>	Power Supply (V <sub>CC</sub> = 0)		-8.0 to 0	Vdc
VI	Input Voltage (V <sub>CC</sub> = 0)		0 to V <sub>EE</sub>	Vdc
l <sub>out</sub>	Output Current	Continuous Surge	50 100	mA
T <sub>A</sub>	Operating Temperature Range		0 to +75	°C
T <sub>stg</sub>	Storage Temperature Range	Plastic Ceramic	−55 to +150 −55 to +165	°C °C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

Table 2. ELECTRICAL CHARACTERISTICS (V<sub>EE</sub> = -5.2 V  $\pm 5\%$ ) (Note 1)

		<b>0</b> °		25°		<b>75</b> °		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
ΙΕ	Power Supply Current	-	29	_	26	_	29	mA
I <sub>inH</sub>	Input Current High (Pin 12 only)	- -	425 850	- -	265 535	- -	265 535	μΑ
I <sub>inL</sub>	Input Current Low	0.5	_	0.5	_	0.3	_	μΑ
V <sub>OH</sub>	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
V <sub>OL</sub>	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
V <sub>IH</sub>	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
V <sub>IL</sub>	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

<sup>1.</sup> Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50 Ω resistor to –2.0 V.

**Table 3. AC PARAMETERS** 

			<b>0</b> °		25°		75°		
Symbol	Characteristic		Min	Max	Min	Max	Min	Max	Unit
t <sub>pd</sub>	Propagation Delay	Pin 12 Only Exclude Pin 12	0.5 0.5	1.6 1.45	0.5 0.5	1.6 1.5	0.5 0.5	1.7 1.6	ns
t <sub>r</sub>	Rise Time		0.5	2.1	0.5	2.2	0.5	2.3	ns
t <sub>f</sub>	Fall Time		0.5	2.1	0.5	2.2	0.5	2.3	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

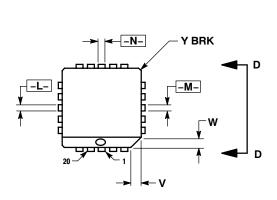
#### **ORDERING INFORMATION**

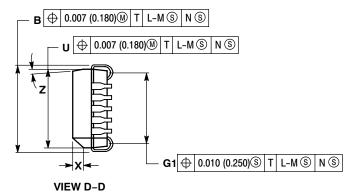
Device	Package	Shipping <sup>†</sup>
MC10H101M	SOEIAJ-16	50 Unit / Rail
MC10H101MG	SOEIAJ-16 (Pb-Free)	50 Unit / Rail
MC10H101MEL	SOEIAJ-16	2000 / Tape & Reel
MC10H101MELG	SOEIAJ-16 (Pb-Free)	2000 / Tape & Reel
MC10H101FN	PLLC-20	46 Units / Rail
MC10H101FNG	PLLC-20 (Pb-Free)	46 Units / Rail
MC10H101FNR2	PLLC-20	500 / Tape & Reel
MC10H101FNR2G	PLLC-20 (Pb-Free)	500 / Tape & Reel
MC10H101L	CDIP-16	25 Unit / Rail
MC10H101P	PDIP-16	25 Unit / Rail
MC10H101PG	PDIP-16 (Pb-Free)	25 Unit / Rail

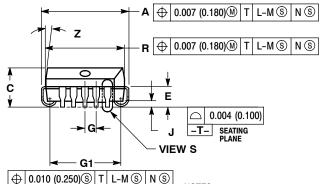
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

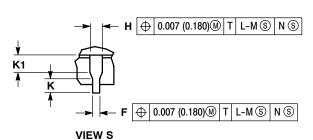
#### PACKAGE DIMENSIONS

#### **20 LEAD PLLC** CASE 775-02 **ISSUE E**









- NOTES:
  1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. DIMENSIONS IN INCHES.
  3. DATUMS -L., -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

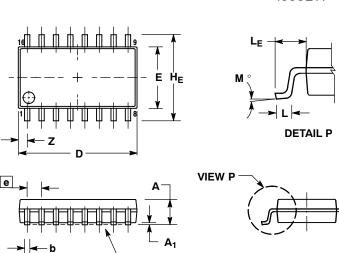
- PARTING LINE.
  4. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM —T-, SEATING PLANE.
  5. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
  6. DIMENSIONS IN THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- PLASTIC BODY.
  7. DIMENSION H DOES NOT INCLUDE DAMBAR DIMIENSION H DUES NOT INCLUDE DAMBAR
  PROTRUSION OR INTRUSION. THE DAMBAR
  PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION
  TO BE GREATER THAN 0.037 (0.940). THE DAMBAR
  INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO
  BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Е	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Χ	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2 °	10°	2°	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

#### PACKAGE DIMENSIONS

#### SOEIAJ-16 CASE 966-01 **ISSUE A**

Q<sub>1</sub>



☐ 0.10 (0.004)

0.13 (0.005) M

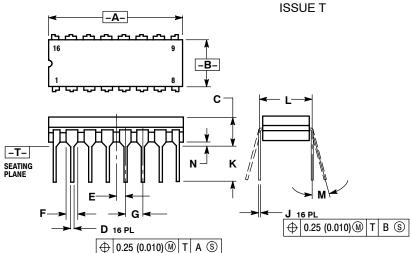
- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI

- NOTES:

  1 DIMENSIONING AND TOLERANCING PER ANSI
  Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS DI AND E DO NOT INCLUDE MOLD
  FLASH OR PROTRUSIONS AND ARE MEASURED
  AT THE PARTING LINE. MOLD FLASH OR
  PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006)
  PER SIDE.
  4. TERMINAL NUMBERS ARE SHOWN FOR
  REFERENCE ONLY.
  5. THE LEAD WIDTH DIMENSION (b) DOES NOT
  INCLUDE DAMBAR PROTRUSION. ALLOWABLE
  DAMBAR PROTRUSION SHALL BE 0.08 (0.003)
  TOTAL IN EXCESS OF THE LEAD WIDTH
  DIMENSION AT MAXIMUM MATERIAL CONDITION.
  DAMBAR CANNOT BE LOCATED ON THE LOWER
  RADIUS OR THE FOOT. MINIMUM SPACE
  BETWEEN PROTRUSIONS AND ADJACENT LEAD
  TO BE 0.46 (0.018).

	MILLIN	METERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α		2.05		0.081	
A <sub>1</sub>	0.05	0.20	0.002	0.008	
b	0.35	0.50	0.014	0.020	
С	0.10	0.20	0.007	0.011	
D	9.90	10.50	0.390	0.413	
Е	5.10	5.45	0.201	0.215	
е	1.27	1.27 BSC		BSC	
HE	7.40	8.20	0.291	0.323	
L	0.50	0.85	0.020	0.033	
LE	1.10	1.50	0.043	0.059	
M	0 °	10 °	0 °	10 °	
Qī	0.70	0.90	0.028	0.035	
Z		0.78		0.031	

### CDIP-16 **L SUFFIX** CERAMIC DIP PACKAGE CASE 620-10 **ISSUE T**



- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

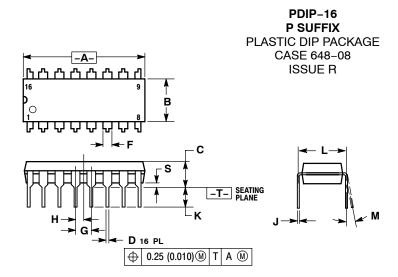
  2. CONTROLLING DIMENSION: INCH.

  3. DIMENSION L TO CENTER OF LEAD WHEN FORMER DANNING.

- FORMED PARALLEL.
  DIMENSION F MAY NARROW TO 0.76 (0.030)
  WHERE THE LEAD ENTERS THE CERAMIC
  BODY.

	INCHES		MILLIN	IETERS	
DIM	MIN MAX		MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
Е	0.050	BSC	1.27	BSC	
F	0.055	0.065	1.40	1.65	
G	0.100	0.100 BSC		BSC	
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62 BSC		
M	0 °	15°	0°	15°	
N	0.020	0.040	0.51	1.01	

#### PACKAGE DIMENSIONS



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIN	METERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100 BSC		2.54 BSC		
Н	0.050 BSC		1.27	BSC	
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	

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